

HOPELEX PCN-2001W

Polycarbonate compound resin

General information

Description

Medium viscosity, easy mold release
Available in white color only

Applications

Multi purpose grade (electric/electronic housings, etc.)

Typical properties¹

	Test method	Typical value	Unit	
Physical				
Melt Flow Index, 300°C, 1.2 kg	ASTM D1238	-	g/10 min	
Specific Gravity	ASTM D792	1.2		
Mold Shrinkage	ASTM D955	0.5~0.7	%	
Mechanical				
Tensile Strength, yield, 50 mm/min	ASTM D638	650	kg _f /cm ²	
Tensile Elongation, break, 50 mm/min	ASTM D638	> 100	%	
Flexural Strength, yield, 10 mm/min	ASTM D790	900	kg _f /cm ²	
Flexural Modulus, 10 mm/min	ASTM D790	24,000	kg _f /cm ²	
IZOD Impact Strength, notched, 23°C, 1/8"	ASTM D256	75	kg _f -cm/cm	
	notched, 23°C, 1/4"	ASTM D256	-	kg _f -cm/cm
	notched, -30°C, 1/8"	ASTM D256	-	kg _f -cm/cm
Thermal				
Heat Distortion Temp.	4.6 kg _f /cm ²	ASTM D648	-	°C
	18.6 kg _f /cm ²	ASTM D648	130	°C
Vicat Softening Temp.	Rate B/50	ASTM D1525	-	°C
Flammability				
UL94 V-2	UL94	1.5	mm	
UL94 V-2	UL94	3.0	mm	

Notes

ISO 9001, 14001, TS 16949

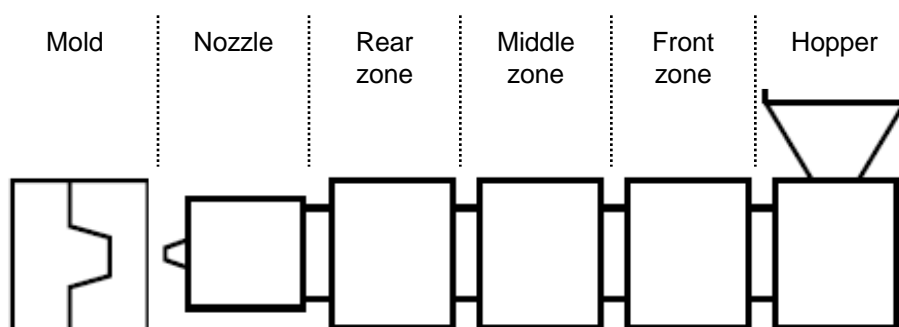
¹ Typical properties : these are not to be construed as specifications.

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Processing guides¹

	Typical value	Unit
Drying condition		
Drying temperature	120	°C
Drying time	4	hr
Maximum moisture content	0.02	%
Injection molding		
Melt temperature	290 ~ 310	°C
Nozzle temperature	280 ~ 300	°C
Barrel	Rear zone	290 ~ 310
	Middle zone	280 ~ 300
	Front zone	270 ~ 290
Hopper temperature	60 ~ 80	°C
Mold temperature	60 ~ 90	°C



Recycling

Sprues and runners can be reground with virgin resin within the ratio of 20%. Care must be taken to ensure that the regrind is free from impurities and regrind should not be used in applications where impact performance and/or agency compliance are required.

Notes

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¹ Processing guides : Typical processing parameters are noted. Actual processing conditions will depend on machine size, mold design, material residence time, shot size, etc.